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FORM PTO-1595 (Modified 09/1995)	U.S. DEPARTMENT OF COMMERCE
RECOR ^{® -}	21-2001 .ET
DMB No. 0651-0011 (exp. 4/94)	
To the Honorable Commissioner of Patents and Trademarks:	818463 Please record the attached original documents or copy thereof
1. Name of conveying party(ies:)	2. Name and address of receiving party(ies)
Rongxiang Hu, Philippe Schoenborn, and	Name: LSI Logic Corporation
Masaichi Eda 8-13-01	Internal Address:
dditional name(s) of conveying party(ies) attached? 🔲 Yes 🛛 No	
3. Nature of conveyance:	Street Address: 1551 McCarthy Boulevard
🛛 Assignment 🛛 Merger	
Security Agreement Change of Name	City: <u>Milpitas</u> State: <u>CA</u> ZIP: <u>95035</u>
	Additional name(s) & address(es) attached? 🗋 Yes 🖄 No
□ Other	
xecution Date: <u>Aug. 10, 2001; Aug. 9, 2001; Aug. 9, 2001</u>	
Application number(s) or patent number(s):	
If this document is being filed together with a new applic	ation, the execution date of the application is: 08/09/01
A. Patent Application No.(s)	B. Patent No.(s)
A. Patent Application No.(5)	D. Patent No.(5)
Additional numbers att	lached? 🗋 Yes 📓 No
5. Name and address of Party to whom correspondence	6. Total number of applications and patents
concerning document should be mailed:	
Name: John R. Ley	involved:
Internal Address:	7. Total fee (37 CFR 3.41)\$40.00
Street Address: <u>Suite 610</u> 5299 DTC Boulevard	Authorized to be charged to deposit account
City: Greenwood Village State: Co ZIP: 80111-3327	8. Deposit account number:
20/2001 LMUELLER 00000100 122252 09928570	12-2252 (Attach duplicate copy of this page if paying by deposit account)
 Statement and signature. To the best of my knowledge and belief, the foregoing it 	information is true and correct and any attached copy is a true
copy of the original document.	
L. Jon Lindsay	August 13, 2001
Name of Person Signing	
	2
Total number of pages including cover sl	heet, attachments, and document:
	PATENT

REEL: 012078 FRAME: 0813

ASSIGNMENT OF APPLICATION

Docket Number : 01-099

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged,

We, the undersigned,

do hereby sell, assign, and transfer to:

LSI LOGIC CORPORATION, a corporation of Delaware, having a place of business at 1551 McCarthy Boulevard, Milpitas, California 95035, ("Assignee"), its successors, assigns, and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all inventions and improvements which are disclosed in the application for United States Letters Patent,

which has been executed by the undersigned concurrently herewith,

and which is entitled:

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in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application; and

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications to patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

First named inventor

Name

H 08/15/51 Date: Rongxiang Hu

Mr. Shizhbarh 8/9/01 Second named inventor Date: Name Philippe Schoenborn

Witness Signature: Witness Printed Name: Witness Address:

Witness Signature: Witness Printed Name: Witness Address:

Connie del Castella Connie del Castillo

Connie da Catillo Connie del Castillo

LSI Logic Corporation Intellectual Property Corporate Legal Department 1551 McCarthy Blvd., MS D-106 Milpitas, California 95035 ENT REEL: 012078 FRAME: 0814

Third named inventor usai du Eda Date: Name 8/9/01 Masaichi Eda

Witness Signature: Witness Printed Name:

Onnie del Castillo

Witness Address:

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RECORDED: 08/13/2001